PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Klaus Pressel	06/08/2007
Adolf Koller	07/26/2007
Horst Theuss	07/26/2007

RECEIVING PARTY DATA

Name:	Infineon Technologies AG
Street Address:	Am Campeon 1-12
City:	Neubiberg
State/Country:	GERMANY
Postal Code:	85579

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11765074

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 1431.211.101

NAME OF SUBMITTER: Steven E. Dicke

Total Attachments: 1

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PATENT

REEL: 019711 FRAME: 0071

\$40.00

ASSIGNMENT

For good and valuable consideration, we, Klaus Pressel, a citizen of Germany, residing at Roter-Brach-Weg 126, 93049 Regensburg, Germany, Adolf Koller, a citizen of Germany, residing at Gebhardstr. 5, 93059 Regensburg, Germany, and Horst Theuss, a citizen of Germany, residing at Brunnweg 7, 93173 Wenzenbach, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on <u>June 19, 2007</u>

US. Serial No. 11/765,074,

entitled: SINGULATING SEMICONDUCTOR WAFERS TO FORM SEMICONDUCTOR CHIPS

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignce, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements an the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned. DATE: 8.6. 2007

SIGNATURE:

NAME: Horst Theuss

DATE: 26.07.07

RECORDED: 08/17/2007

DATE: 26-07.07

PATENT REEL: 019711 FRAME: 0072